

TECHNICAL DATA SHEET

2006

In order to help heat management of Electronic devices, Silicon based, 2-Component, Heat Curable or Room Temperature curable Potting with good thermal conductivity.

FEATURES & BENEFITS

- Low viscosity for good flowability.
- Low surface tension, Simple mix Ratio 1:1
- Good Thermal conductivity

APPLICATIONS

2006 A & B is designed to provide efficient heat transfer in electronic modules, including power supply. It is used in power electronic components, modular power supplies, circuit boards for potting application, LED drivers, automotive HID lamp power supply, automotive ignition system module power supply, network transformers, adaptors, inverters, transformers, sensors, electronics control units etc.

MIXING AND DE-AIRING

On Storage for few weeks, some sedimentation occurs, to ensure a uniform product mixing and performance the material in each container should be thoroughly mixed prior to use. Two-part material must be mixed in 1:1 ratio either by weight or volume. The presence of light-colored streaks or any color variation indicates inadequate mixing.

USEFUL TEMPERATURE RANGES

Operational over a temperature range of -45 to 150°C

for long periods of time. At high-temperature end, the durability of the cured silicone is mostly time and temperature dependent. Most of the times, the higher the temperature, the shorter the time the material will remain useable.

USABLE LIFE AND STORAGE

The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by the indicated "Exp. Date" found on the label.

PACKING

25kg/can

INFORMATION

The data provided here is standard data and under certain conditions, In various conditions the data may differ and Electo Advises to do a test on your own before using the material.

TYPICAL PROPERTY DATA

Property	Unit	Result
One part or Two part		Two
Color		Gray/White/
Mix Ratio		1:1
Viscosity (Part A)	cP	9500 app.
Viscosity (Part B)	cP	4200 app.
Viscosity (Mixed)	cP	6700 app.
Specific Gravity-Cured		2.20
Working Time at 25°C	Hours	2
Heat Cure at 120°C	Minutes	30
Durometer	Shore OO	45
Penetration	1/10 mm	32
Elongation	%	400
Tensile Strength	mPa	4.3
Dielectric Strength	kV/mm	18
Dielectric Constant	100 Hz/ KHz	4.6
Dissipation Factor	100 Hz	0.002
Volume Resistivity	Ohm-cm	1.90E+14
Coefficient of Linear Thermal Expansion (CTE)	ppm/°C	175
Thermal Conductivity	W/mK	0.60

